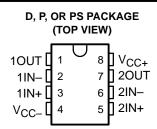
TL4581 DUAL LOW-NOISE HIGH-DRIVE OPERATIONAL AMPLIFIER

SLVS457A - JANUARY 2003 - REVISED MARCH 2003

- Equivalent Input Noise Voltage
 5 nV/√Hz Typ at 1 kHz
- Unity-Gain Bandwidth . . . 10 MHz Typ
- High Slew Rate . . . 9 V/μs Typ
- Peak-to-Peak Output Voltage Swing
 32 V Typ, With V_{CC±} = ±18 V and R_L = 600 Ω
- Wide Supply-Voltage Range . . . ±3 V to ±20 V
- Common-Mode Rejection Ratio . . . 100 dB Typ
- High dc Voltage Gain . . . 100 V/mV Typ
- Applications: Audio PreAmps, Active Filters, Headphone Amps
- End Equipment: DVD/CD/CDRW Players;
 Set-Top Boxes



description/ordering information

The TL4581 is a dual operational amplifier that has been designed optimally for audio applications, such as improving tone control. It offers low noise, high-gain bandwidth, good slew, and high output current drive for driving capacitive loads. These features make the TL4581 ideally suited for audio applications, such as audio preamps and active filters. When high output current is required, the TL4581 also can be used as a headphone amplifier.

ORDERING INFORMATION

TA	PAC	KAGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – P	Tube of 50	TL4581P	TL4581P
0°C to 70°C	SOIC - D	Tube of 75	TL4581D	T4581
0°C to 70°C	30IC - D	Reel of 2500	TL4581DR	14361
	SOP – PS	Reel of 2000	TL4581PSR	T4581

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage (see Note 1): V _{CC+}		22 V
Input voltage, either input (see Notes 1 and 2)		V _{CC±}
Input current (see Note 3)		±10 mA
Duration of output short circuit (see Note 4)		Unlimited
Operating virtual junction temperature, T _J		150°C
Package thermal impedance, θ_{JA} (see Notes 5 and 6):	: D package	97°C/W
	P package	85°C/W
	PS package	95°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10	seconds	260°C
Storage temperature range, T _{stg}		. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-}.

- 2. The magnitude of the input voltage must never exceed the magnitude of the supply voltage.
- 3. Excessive input current will flow if a differential input voltage in excess of approximately 0.6 V is applied between the inputs, unless some limiting resistance is used.
- 4. The output may be shorted to ground or either power supply. Temperature and/or supply voltages must be limited to ensure the maximum dissipation rating is not exceeded.
- 5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- 6. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		MIN	MAX	UNIT
V _{CC+}	Supply voltage	5	15	V
VCC-	Supply voltage	- 5	-15	V
TA	Operating free-air temperature range	0	70	°C



electrical characteristics, $V_{CC^{\pm}}$ = +15 V, T_A = 25°C (unless otherwise noted)

	PARAMETER	TE	ST CONDITIONS		MIN	TYP	MAX	UNIT
\/	Input offset voltage	V _O = 0	T _A = 25°C			0.5	4	mV
VIO	input onset voltage	ΛQ = 0	$T_A = 0^{\circ}C$ to $70^{\circ}C$				5	IIIV
li a	Input offset current	T _A = 25°C				10	150	nA
lio	input onset current	$T_A = 0$ °C to 70 °C					200	ПА
I _{IB}	Input bias current	T _A = 25°C				200	800	nA
I JIR	input bias current	$T_A = 0^{\circ}C$ to $70^{\circ}C$					1000	ША
VICR	Common-mode input-voltage range				±12	±13		V
V	Maximum peak-to-peak	R _I ≥ 600 Ω	$V_{CC\pm} = \pm 15 \text{ V}$		24	26		٧
VOPP	output-voltage swing	KL 2 000 12	V _{CC±} = ±18 V		30	32		V
		R _L ≥ 600 Ω,	T _A = 25°C		15	50		
۸ــ	Large-signal differential-voltage amplification	$V_{O} = \pm 10 \text{ V}$	$T_A = 0$ °C to 70°C	10			V/mV	
AVD		$R_L \ge 2 k\Omega$,	T _A = 25°C		25	100		V/IIIV
		V _O = ±10 V	$T_A = 0$ °C to 70°C	15				
A _{vd}	Small-signal differential-voltage amplification	f = 10 kHz				2.2		V/mV
D	Maximum autout aving handwidth	R _I = 600 Ω	V _O = ±10 V			140		kHz
Вом	Maximum-output-swing bandwidth	K[= 000 22	$V_{CC\pm} = \pm 18 \text{ V},$	V _O = ±14 V		100		KΠZ
B ₁	Unity-gain bandwidth	$R_L = 600 \Omega$,	C _L = 100 pF			10		MHz
rį	Input resistance				30	300		kΩ
z _O	Output impedance	$A_{VD} = 30 \text{ dB},$	$R_L = 600 \Omega$,	f = 10 kHz		0.3		Ω
CMRR	Common-mode rejection ratio	V _{IC} = V _{ICR} min			70	100		dB
ksvr	Supply-voltage rejection ratio (ΔV _{CC±} /ΔV _{IO})	$V_{CC\pm} = \pm 9 \text{ V to } \pm$	15 V,	V _O = 0	80	100		dB
los	Output short-circuit current				10	38	60	mA
ICC	Total supply curent	V _O = 0,	No load			8	16	mA
	Crosstalk attenuation (VO1/VO2)	V ₀₁ = 10 V peak,	f = 1 kHz			110		dB

[†] All characteristics are measured under open-loop conditions with zero common-mode input voltage, unless otherwise specified.

operating characteristics, $V_{CC\pm}$ = ± 15 V, T_A = $25^{\circ}C$

	PARAMETER	TEST CON	IDITIONS	MIN	TYP	MAX	UNIT
SR	Slew rate at unity gain				9		V/μs
	Overshoot factor	V_I = 100 mV, R_L = 600 Ω ,	$A_{VD} = 1,$ $C_{L} = 100 \text{ pF}$		10		%
	Equivalent input noise voltage	f = 30 Hz			8		nV/√ Hz
V _n	Equivalent input noise voltage	f = 1 kHz			5		nv/vHz
	Equivalent input poice current	f = 30 Hz			2.7	, and the second	pA/√Hz
l'n	Equivalent input noise current	f = 1 kHz			0.7	, and the second	p∧√√⊓Z

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
TL4581D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL4581DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL4581DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL4581DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL4581DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL4581DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL4581P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL4581PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TL4581PSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL4581PSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL4581PSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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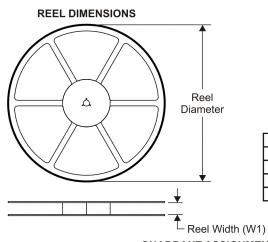


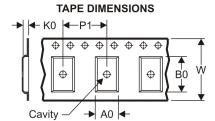
PACKAGE OPTION ADDENDUM

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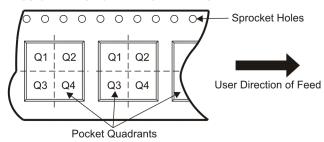
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

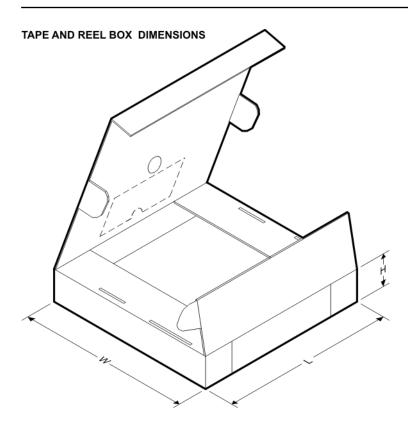
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

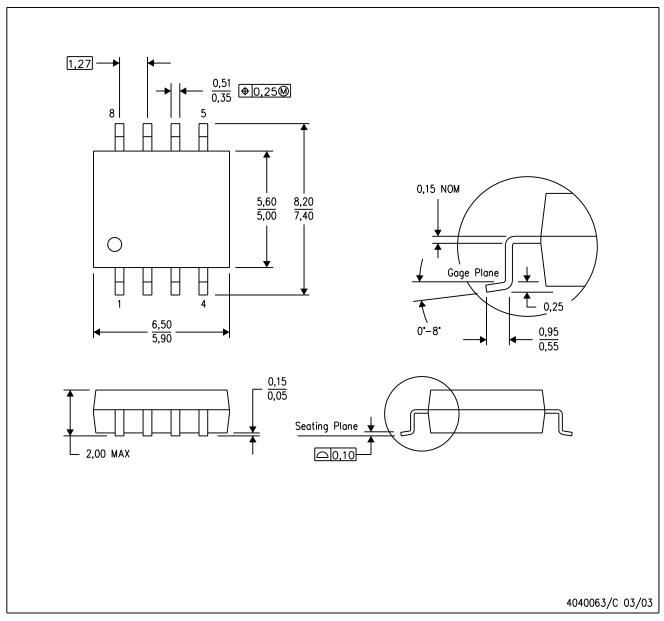
	Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
I	TL4581DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
	TL4581PSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL4581DR	SOIC	D	8	2500	340.5	338.1	20.6
TL4581PSR	SO	PS	8	2000	346.0	346.0	33.0



NOTES: A. All linear dimensions are in millimeters.

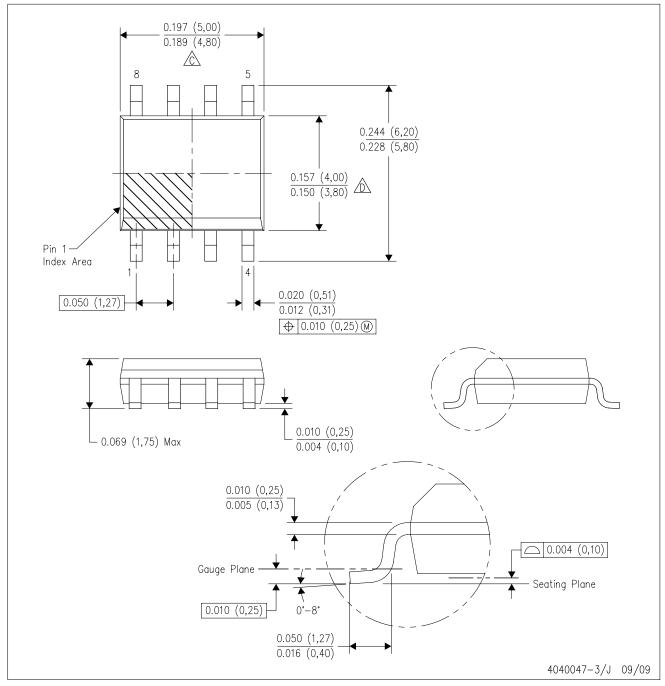
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



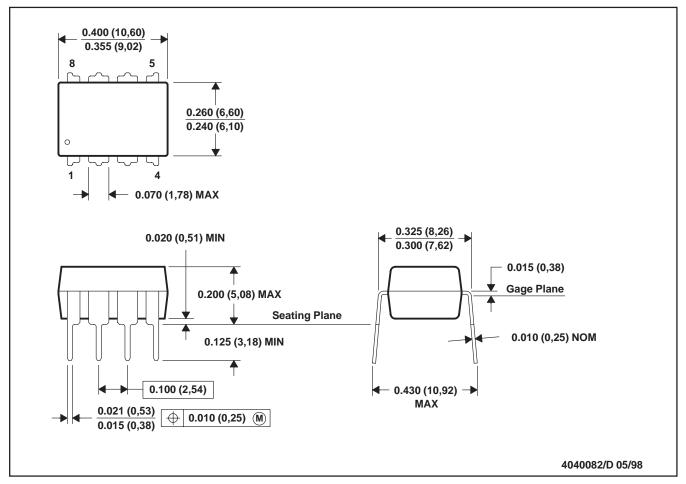
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to $http://www.ti.com/sc/docs/package/pkg_info.htm$